



US00D395638S

United States Patent [19]

Koyama et al.

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[54] **SEMICONDUCTOR PACKAGE**

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[73] Assignee: **Sony Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **65,265**

[22] Filed: **Jan. 30, 1997**

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; 174/52.2-52.4; 206/710, 719; 257/254, 659, 666-678, 697, 730, 738, 780, 796; 361/730; 437/183, 217, 220

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[57] **CLAIM**

The ornamental design for a semiconductor package, as shown and described

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor package showing our new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a rear elevational view thereof;
FIG. 8 is a perspective view of another embodiment of a semiconductor package showing our new design; and,
FIG. 9 is a front elevational view of the embodiment of FIG. 8.
The rest of veivs of the embodiment of FIG. 8 are the same as those of the embodiment of FIG. 1.

1 Claim, 4 Drawing Sheets

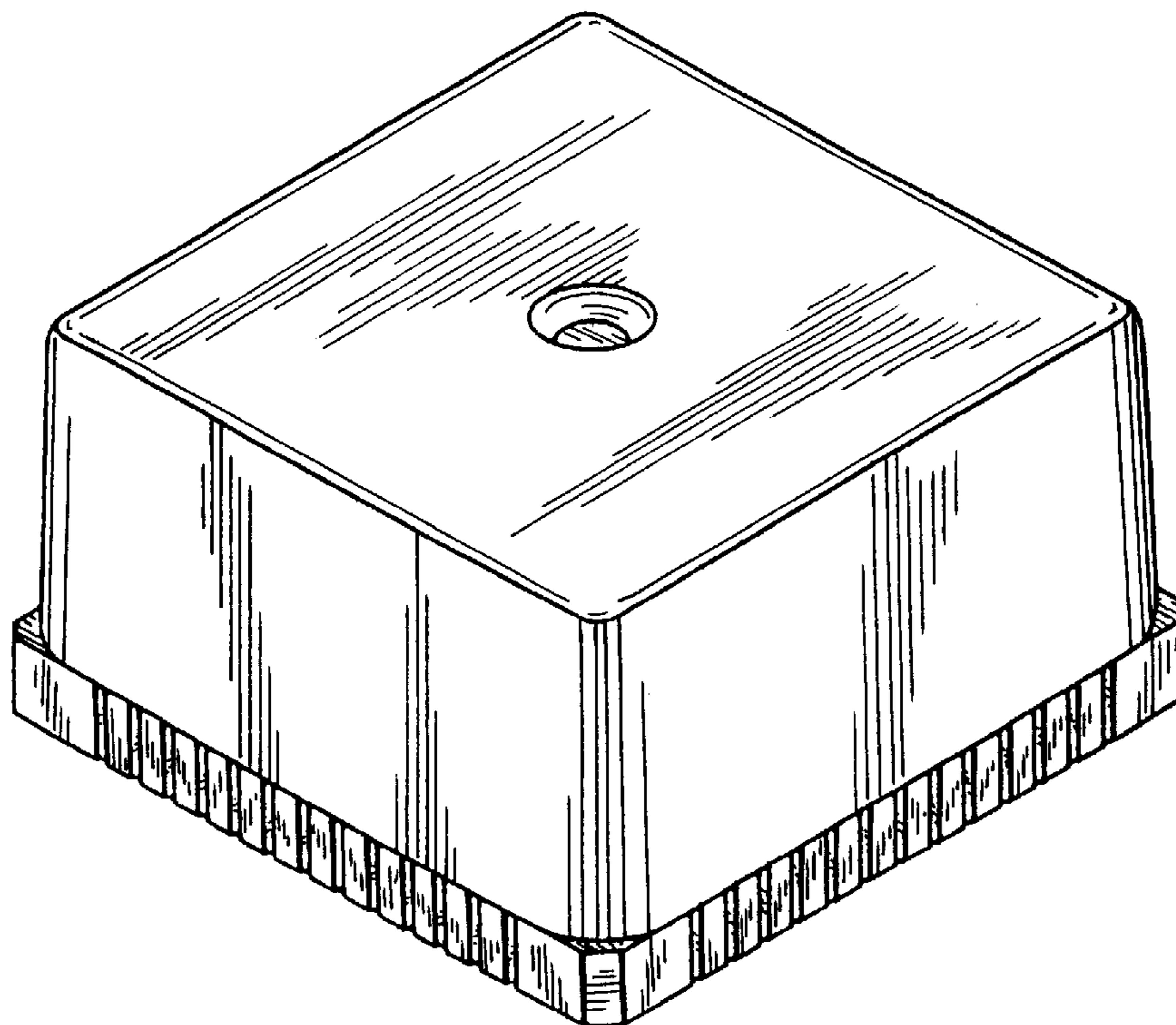


FIG. 1

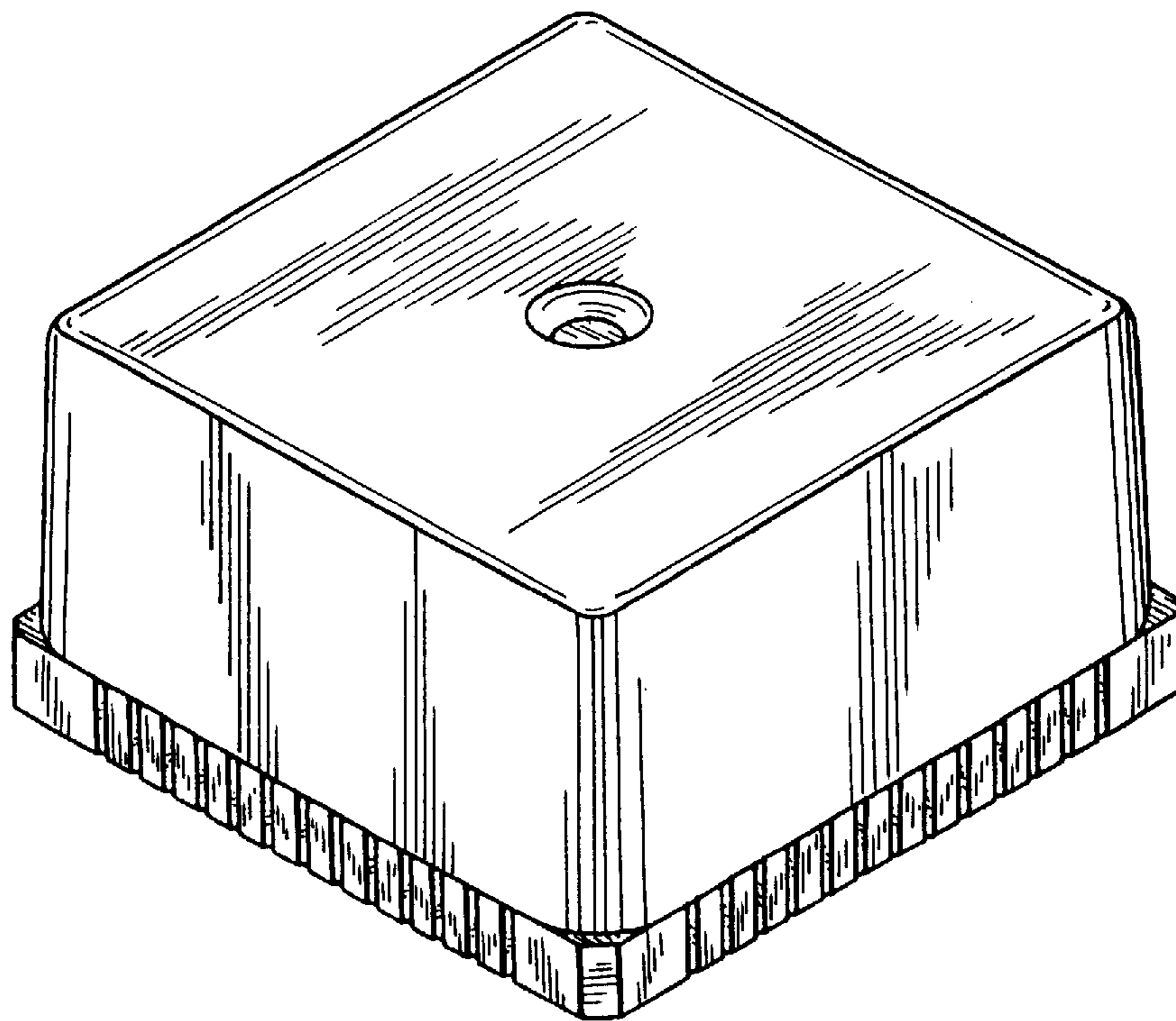


FIG. 2

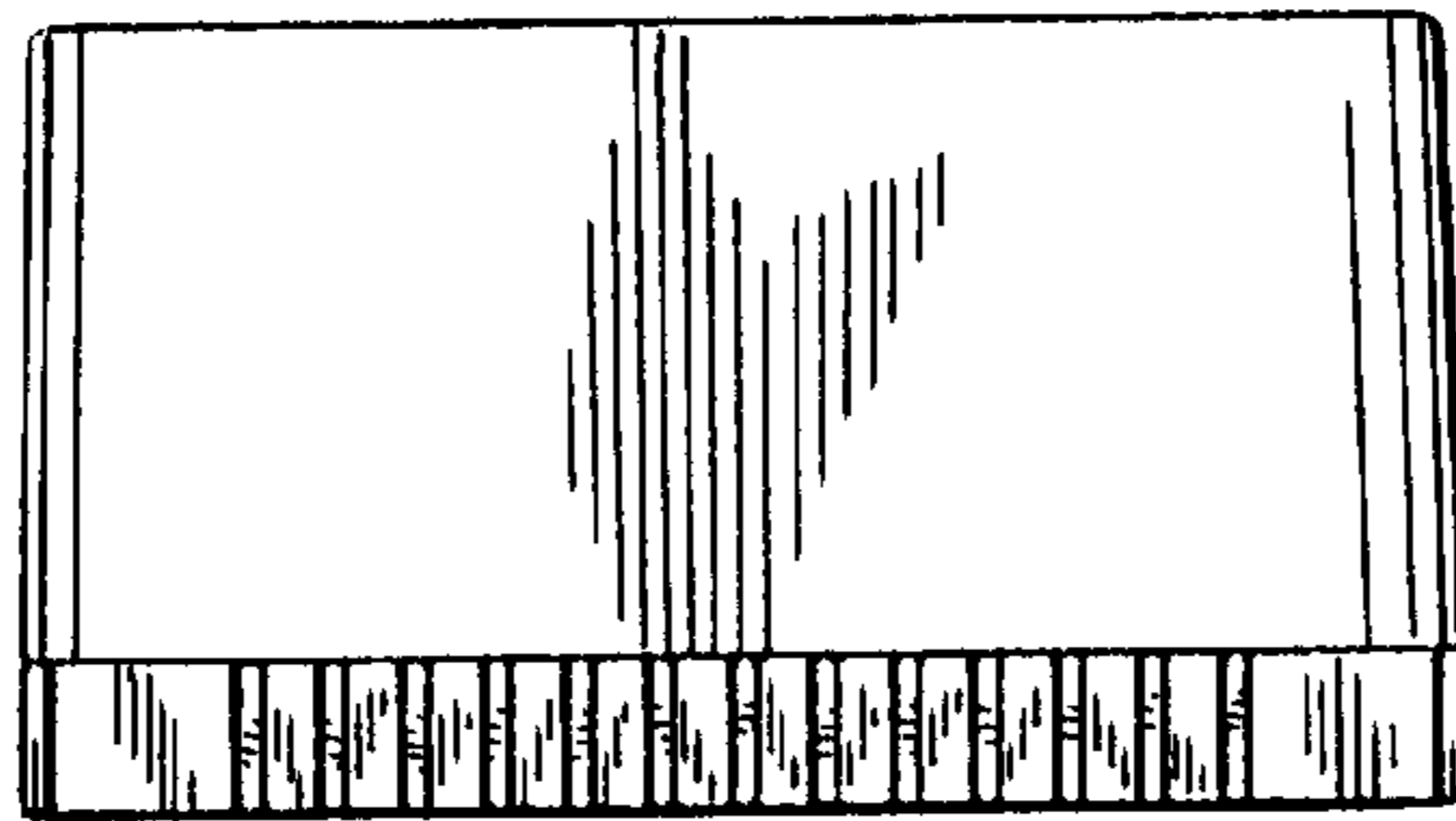


FIG. 4

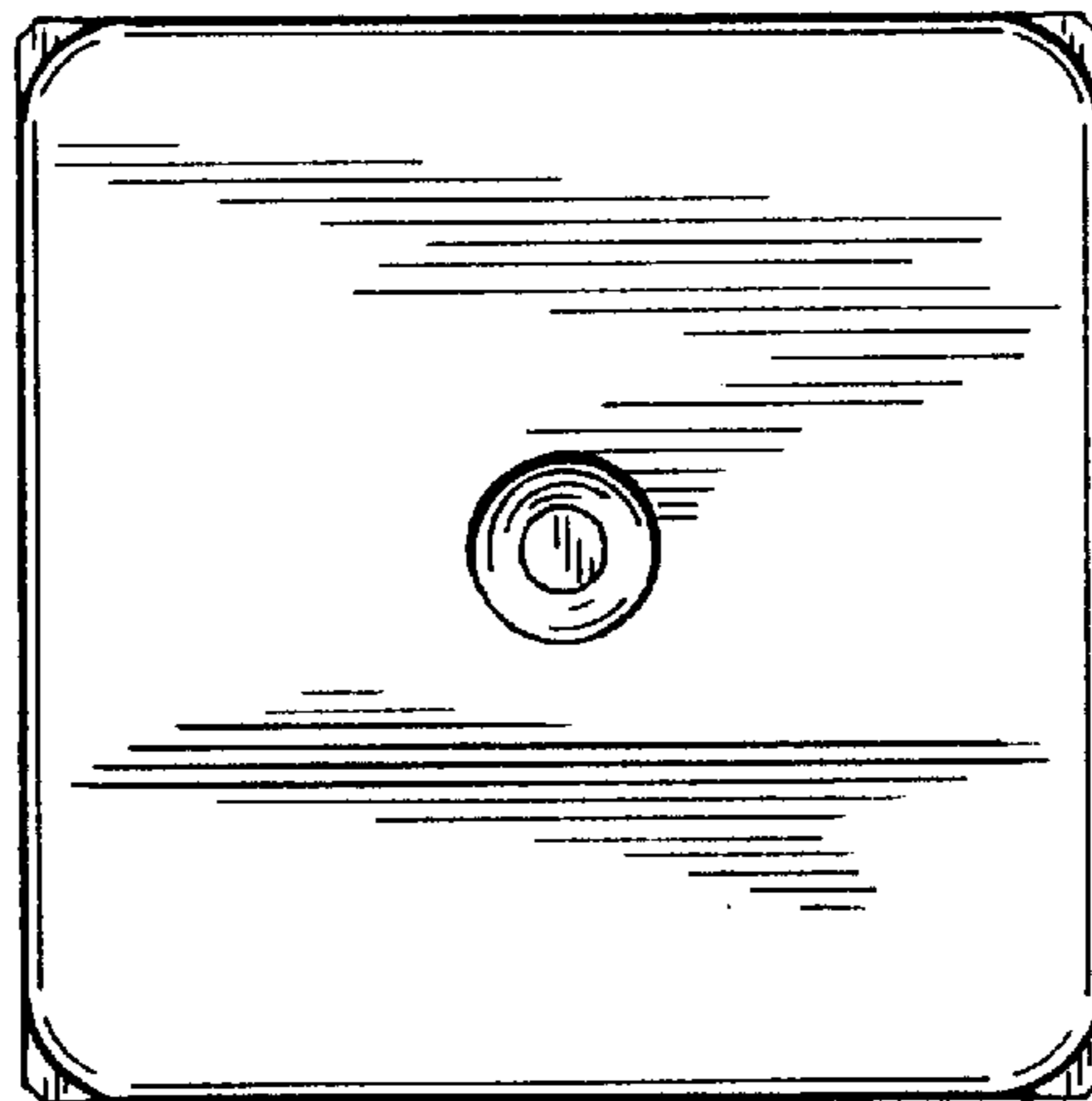


FIG. 5

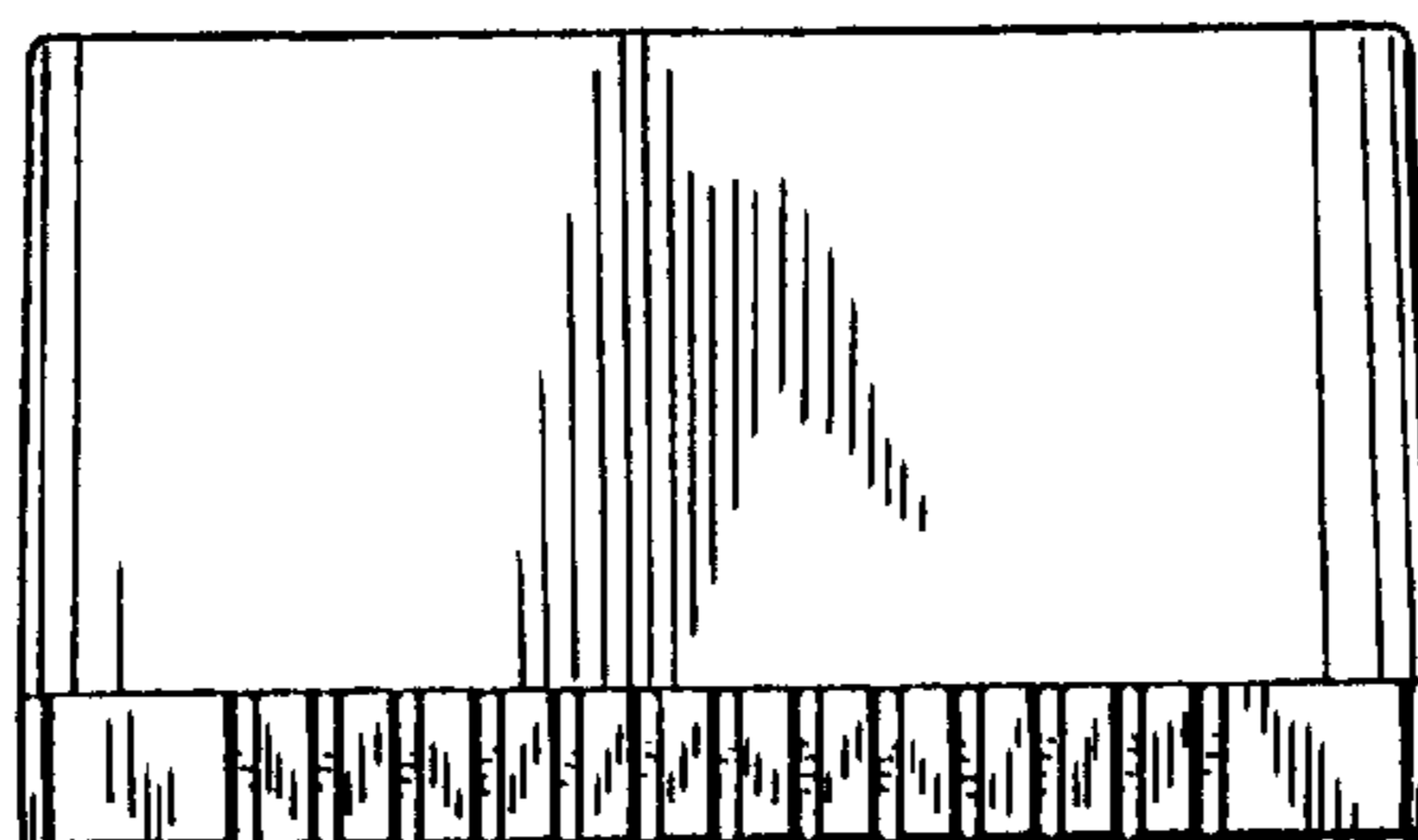


FIG. 3

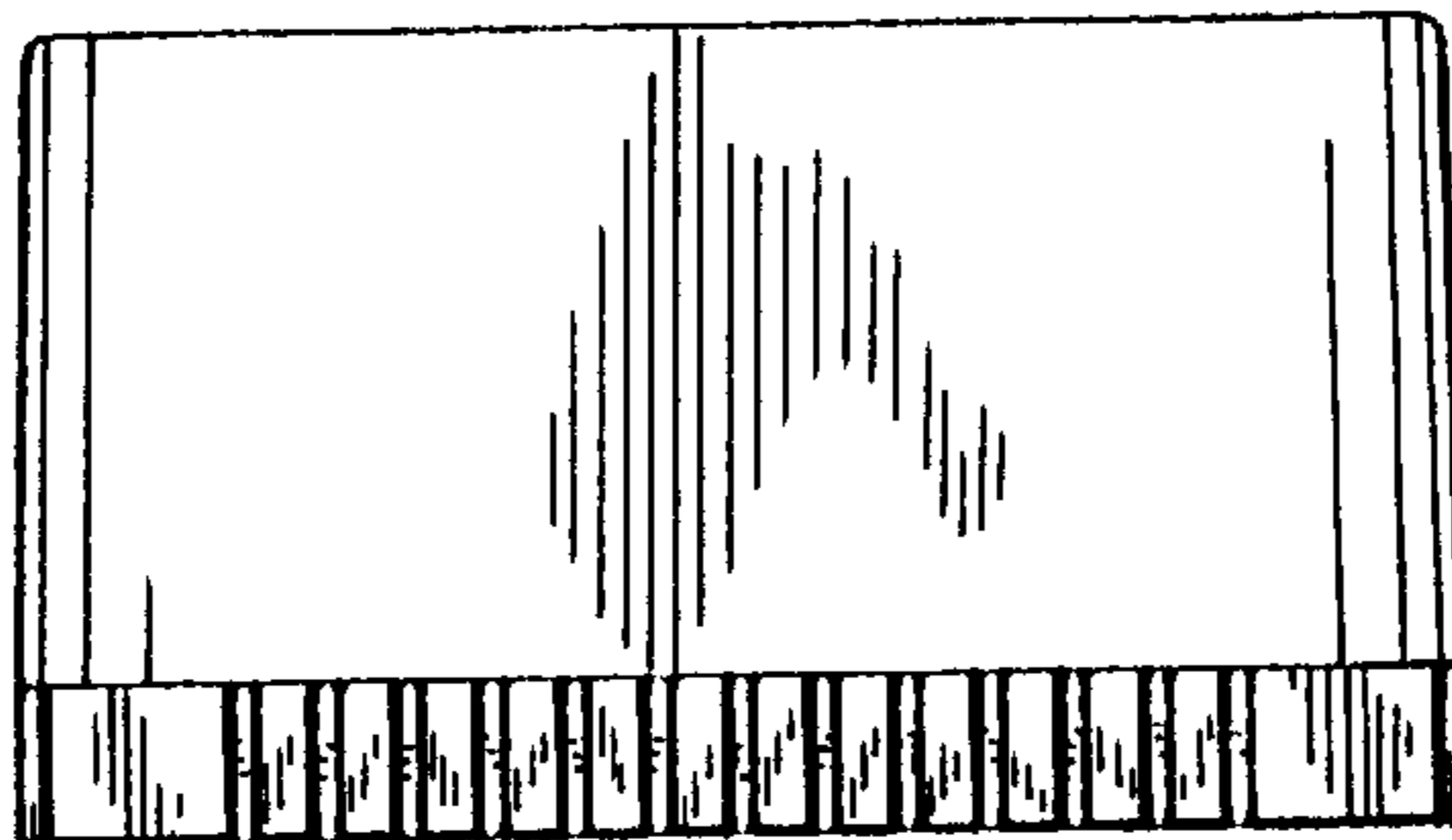


FIG. 7

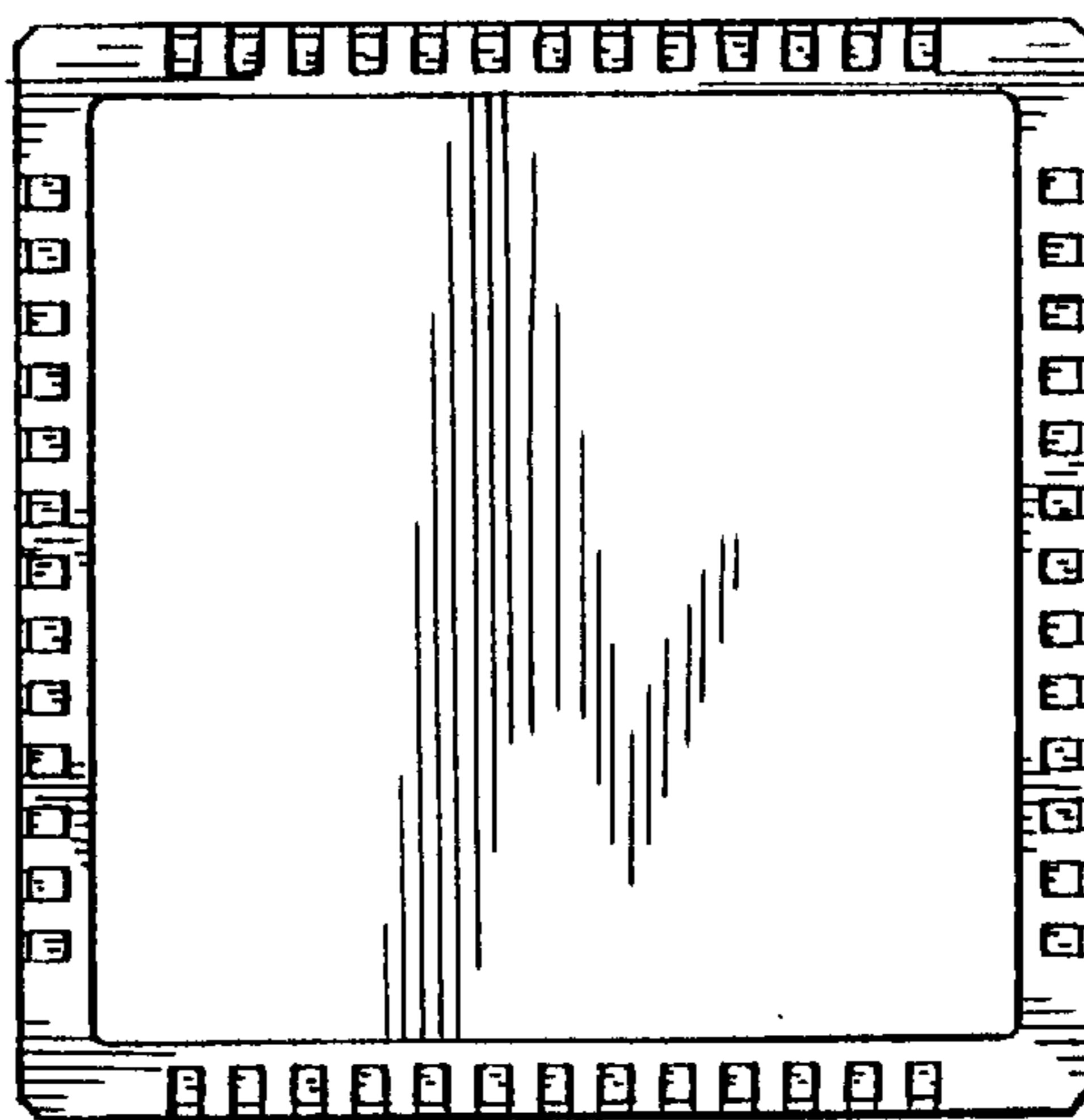


FIG. 6

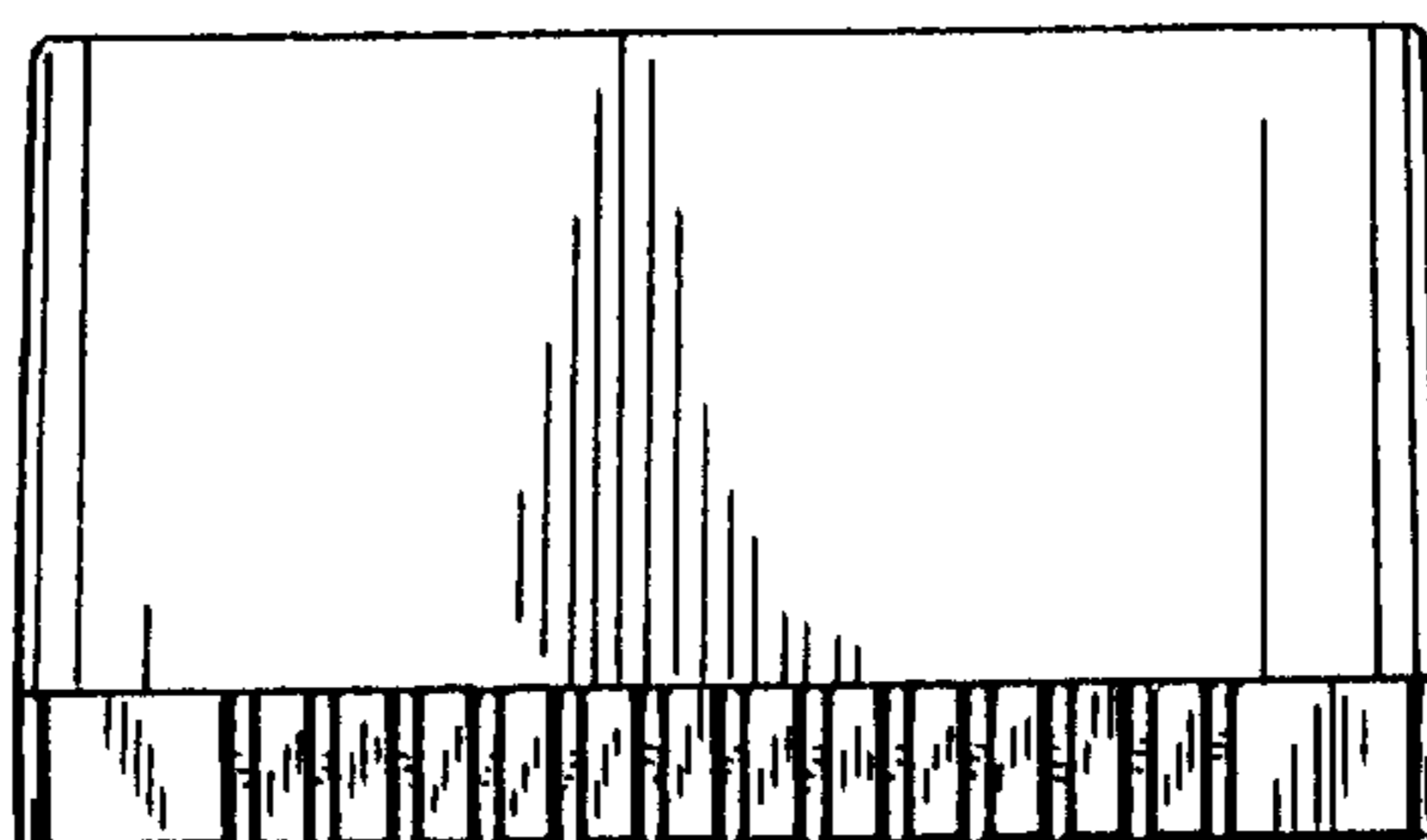


FIG. 8

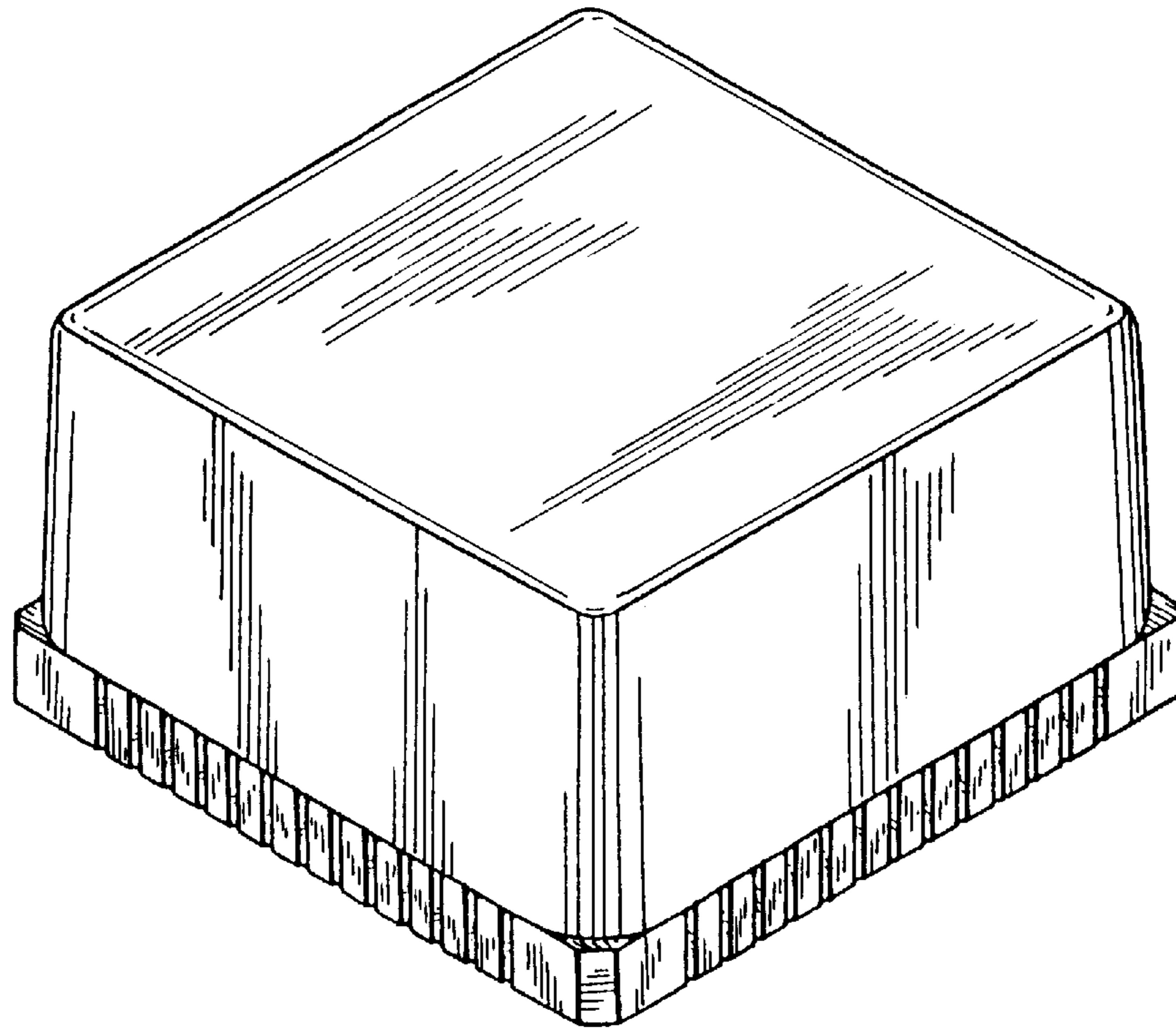


FIG. 9

